EPOXIES
INNOVATIVE BONDING SOLUTIONS ETC.

TECHNICAL BULLETIN

50-3105
HIGH TEMPERATURE THERMALLY CONDUCTIVE EPOXY

DESCRIPTION:

50-3105 is a thermally conductive adhesive and potting epoxy system. This system is engineered for the most demanding electronic potting, encapsulating, and bonding applications. 50-3105, when used with Catalyst 79 provides high temperature and chemical resistance and low thermal expansion.

TYPICAL SPECIFICATIONS:

Viscosity @ 25°C, cps	Semi-solid paste
Specific Gravity, Resin, 25°C	1.8
Hardness, Shore D	55-60
Tensile Strength, psi	2100
Thermal Conductivity, W/m-deg K	0.6
Dielectric Strength, Volts/Mil	>375
Dielectric Constant, 1 MHz	5.41
Volume Resistivity, OHM-CM @ 25°C	4.9×10^{16}

INSTRUCTIONS FOR USE:

50-3105 Resin is a semi-solid at room temperature. It must be heated prior to use.

1. Warm resin to 80 deg C. Stir thoroughly.
2. By weight, thoroughly mix 11 parts Catalyst 79 (MTHPA/NT) to 100 parts 50-3105 Resin
3. De-gas mixture
4. Pour
5. De-gas
6. Cure 12 hours at 120 deg C

IMPORTANT:

The information in this brochure is based on data obtained by our own research and is considered accurate. However, no warranty is expressed or implied regarding the accuracy of these data, the results to be obtained from the use thereof, or than any such use will not infringe any patent. This information if furnished upon the condition that the person receiving it shall make his own tests to determine the suitability thereof for his particular purpose.

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